

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 236518US26YA		SERIAL NO. 10/673,138			
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Andrej S. MITROVIC		GROUP 2128			
				FILING DATE September 30, 2003					
U.S. PATENT DOCUMENTS									
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE		
/A.S./	AA	US 6,571,371	5/2003	Coss, et al.					
	AB	US 6,763,277	7/2004	Allen, et al.					
	AC	US 6,529,789	3/2003	Campbell, et al.					
	AD	US 6,628,809	9/2003	Rowe, et al.					
	AE	US 6,728,591	4/2004	Hussey, et al.					
	AF	US 6,774,998	8/2004	Wright, et al.					
	AG	US 2005/0010319	1/2005	Patel, et al.					
	AH	US 2004/0044513	3/2004	Kitahara, Noriaki					
	AI	US 6,615,097	9/2003	Ozaki, Hiroji					
/A.S./	AJ	US 6,618,856	9/2003	Coburn, et al.			Repeated.		
	AK	US 2004/0044513	3/2004	Kitahara, Noriaki					
/A.S./	AL	US 5,539,652	7/23/1996	Tegethoff					
	AM	US 6,581,029 B1	6/17/2003	Fisher					
/A.S./	AN	US 2003/0003607	1/2/2003	Kagoshima et al					
FOREIGN PATENT DOCUMENTS									
				COUNTRY		TRANSLATION			
						YES	NO		
Not provided.				AO CN 1335558A		2/13/2002	China (with Partial English Translation)	X	
/A.S./	AP	JP 2004-527117	9/2/2004	Japan				X	
/A.S./	AQ	WO 03/060779 A1	7/24/2003	WIPO				X	
/A.S./	AR	JP 2005-515623	5/26/2005	JAPAN (With English Abstract)				X	
/A.S./	AS	WO 03/009345 A2	1/30/2003	WIPO				X	
/A.S./	AT	JP 2005-522018	7/21/2005	JAPAN (With English Abstract)				X	
/A.S./	AU	JP 2002-367875	12/20/2002	JAPAN				X	
/A.S./	AV	JP 2003-502771	1/21/2003	JAPAN				X	
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)									
Not provided.				AW Robert W. ATHERTON, et al., "Detailed Simulation for Semiconductor Manufacturing", Proceedings of the 1998 Winter Simulation Conference					
				AX Angus J. MACDONALD, et al., "Integrated CAM and Process Simulation to Enhance On-Line Analysis and Control of IC Fabrication"; IEEE Transactions on Semiconductor Mfg., Vol. 3, No. 2, May 1990					
				AY Yea-Huey SU, et al. "Conceptual Framework for Manufacturing Service Provisioning by Virtual Fabs"; 1998 NSC Republic Of China; 1998 Semiconductor Mfg. Technology Workshop					
				AZ Chanettre RASMIDATTA, et al. "New approaches for Simulation of Wafer fabrication - The Use of Control Variates and Calibration Metrics" Proceedings of 2002 Winter Simulation Conference; 2002					
				<input type="checkbox"/> Additional References sheet(s) attached					
Examiner /Akash Saxena/ (12/14/2010)				Date Considered 12/14/2010					

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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/A.S./	AAA	US 5,377,116	12/1994	Wayne, et al.			
	AAB	US 5,629,877	5/1997	Tamegaya, Yukio			
↓	AAG	US 6,625,497	9/2003	Fairbairn, et al.			
/A.S./	AAD	US 6,185,472	2/6/2001	Onga, et al.			
	AAE						
	AAF						
	AAG						
	AAH						
	AAI						
	AAJ						
	AAK						
	AAL						
	AAM						
	AAN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO		
/A.S./	AAO	JP 2003-17471	1/17/2003	JAPAN (With English Abstract)			X
/A.S./	AAP	WO 02/065511 A2	8/22/2002	WIPO			X
/A.S./	AAO	JP 2004-524685	8/12/2004	JAPAN			X
/A.S./	AAR	WO 02/069063 A2	9/6/2002	WIPO			X
/A.S./	AAS	JP 2004-531878	10/14/2004	JAPAN			X
	AAT						
	AAU						
	AAV						
	AAW						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AAx	Naomi YONEMURA, et al. "Heat Analysis on Insulated Metal Substrates", 1996, IEEE, pgs. 1407-1410					
	AAy	Tony C. MIDEA, et al., "Casting Simulation Software Survey", 1999, pages 1-4					
/A.S./	AAZ	Heru SETYAWAN, et al. "Visualization and numerical simulation of fine particle transport in a low-pressure parallel plate chemical vapor deposition reactor", Chemical Engineering Science 57 (2002) pages 497-506					
						<input type="checkbox"/> Additional References sheet(s) attached	
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/A.S./	AAAA	US 7,047,095 B2	5/16/2006	Tomoyasu			
/A.S./	AAAB	US 6,587,744 B1	7/1/2003	Stoddard, et al.			
	AAAP						
	AAAD						
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FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO		
/A.S./	AAAO	JP 2000-517473	12/26/2000	JAPAN (With English Abstract)			X
/A.S./	AAAP	WO 03/058699 A1	7/17/2003	WIPO			X
/A.S./	AAAO	JP 2005-514790	5/19/2005	JAPAN (With English Abstract)			X
	AAAP						
	AAAS						
	AAAT						
	AAAU						
	AAAV						
	AAAW						
	AAAX						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AAAY						
	AAAZ						
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